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United States Patent [19]

Song et al.

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[45] **Date of Patent: ** Oct. 17, 2000**

[54] **SEMICONDUCTOR PACKAGE**

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[73] Assignee: **Samsung Electronics Co., Ltd.**, Suwon, Rep. of Korea

[**] Term: **14 Years**

[21] Appl. No.: **29/117,450**

[22] Filed: **Jan. 24, 2000**

[30] **Foreign Application Priority Data**

Nov. 20, 1999 [KR] Rep. of Korea 99-27904

[51] **LOC (7) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/182; 174/524, 174/525; 257/690; 361/752, 798, 820

[56] **References Cited**

U.S. PATENT DOCUMENTS

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Primary Examiner—Brian N. Vinson

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[57] **CLAIM**

The ornamental design for a semiconductor package, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view showing our design;

FIG. **2** is a left-hand side view thereof, the right-hand side view being a mirror image thereof;

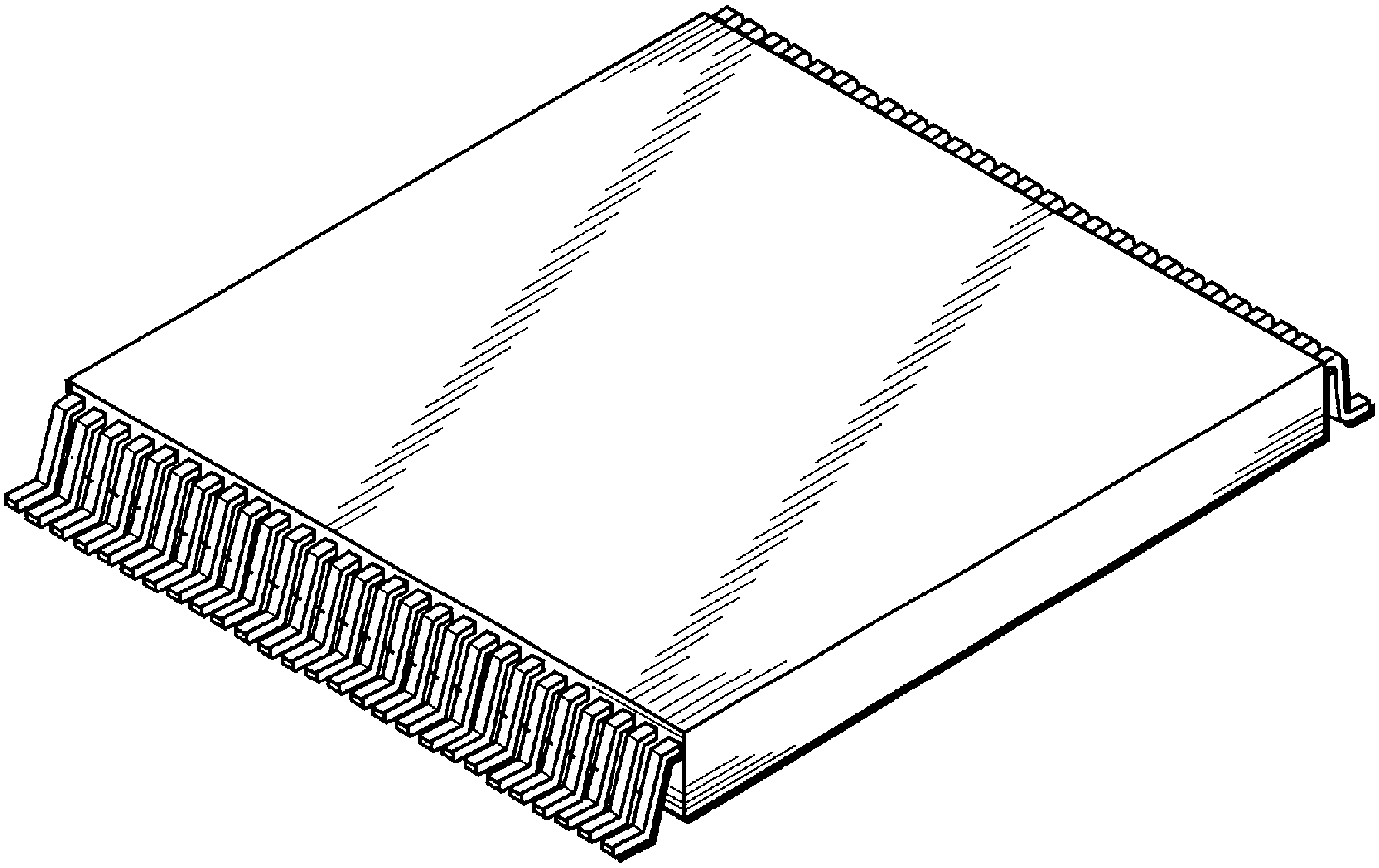
FIG. **3** is a front view thereof, the rear view being identical thereto;

FIG. **4** is a sectional view thereof;

FIG. **5** is a top view thereof; and,

FIG. **6** is a bottom plan view thereof.

1 Claim, 6 Drawing Sheets



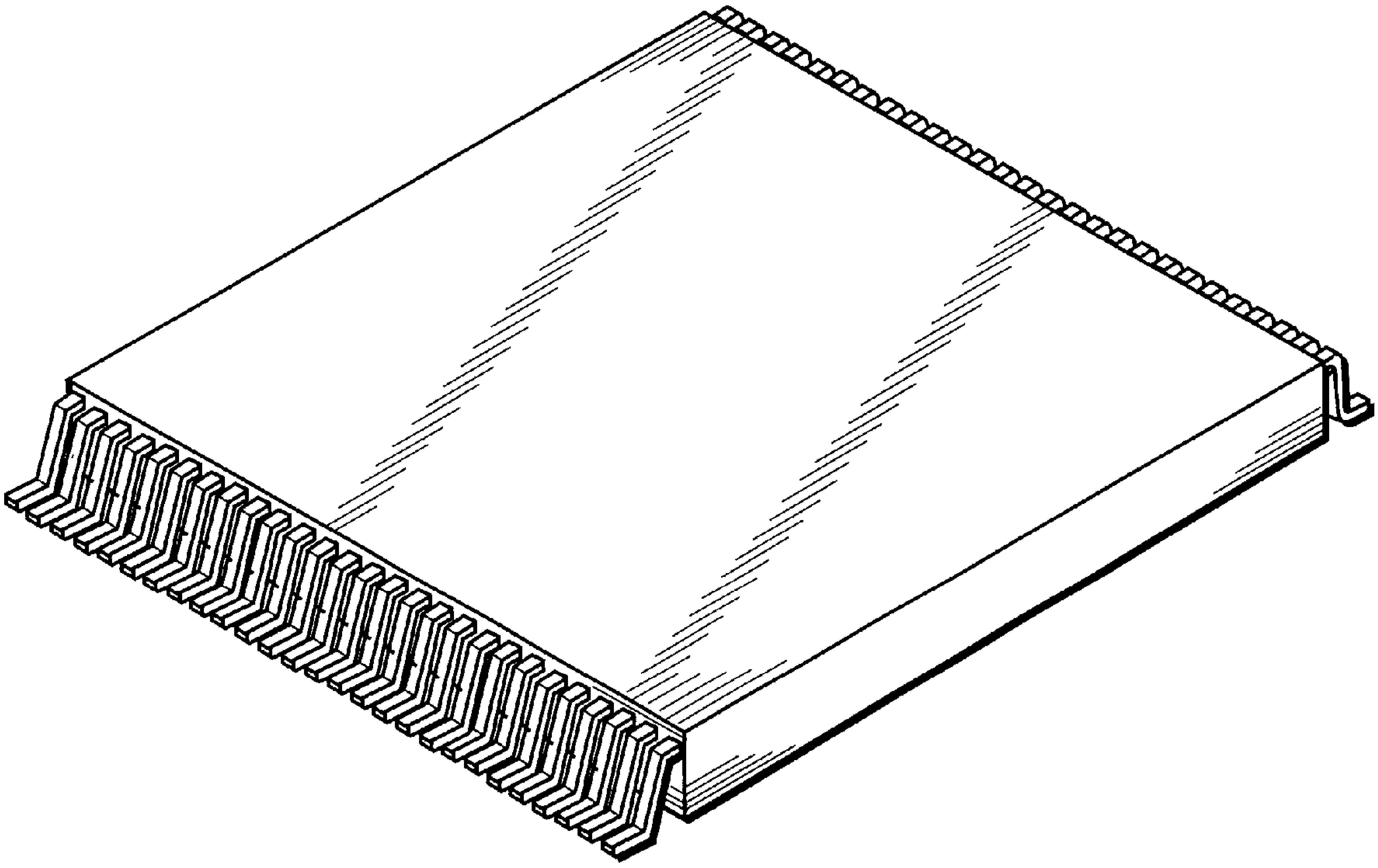


FIG. 1

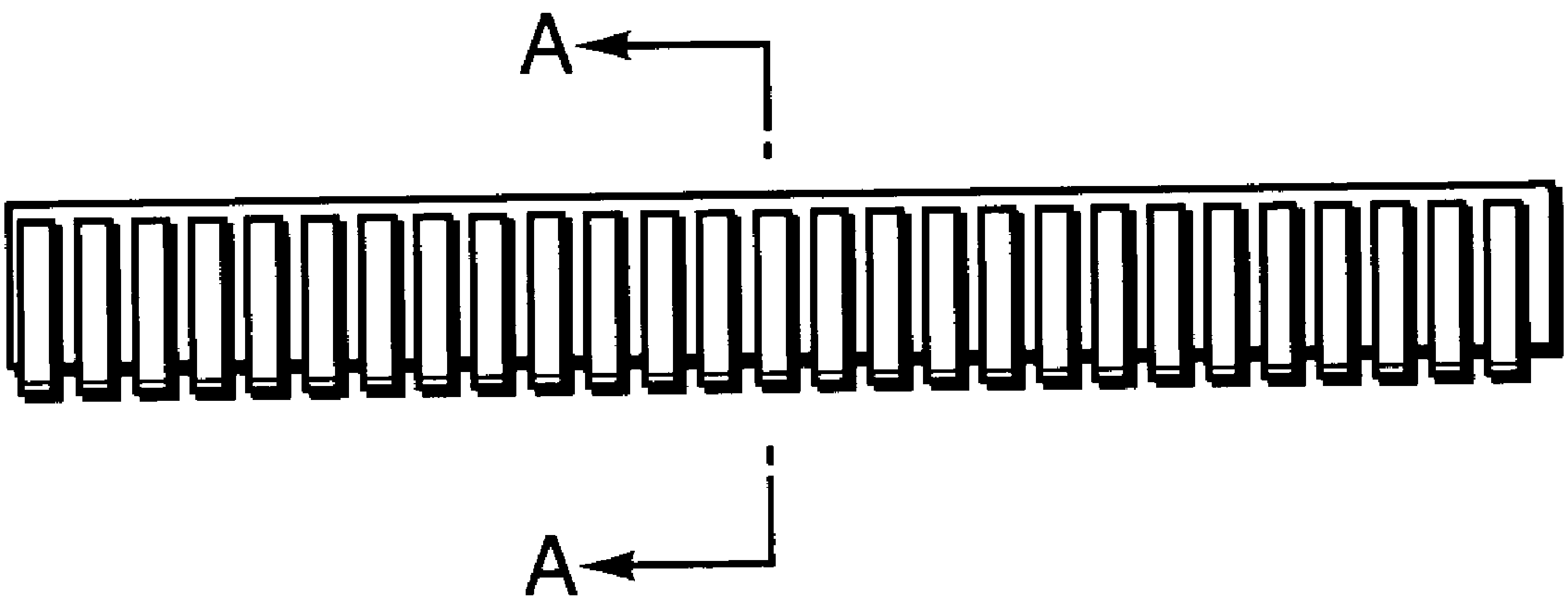


FIG. 2

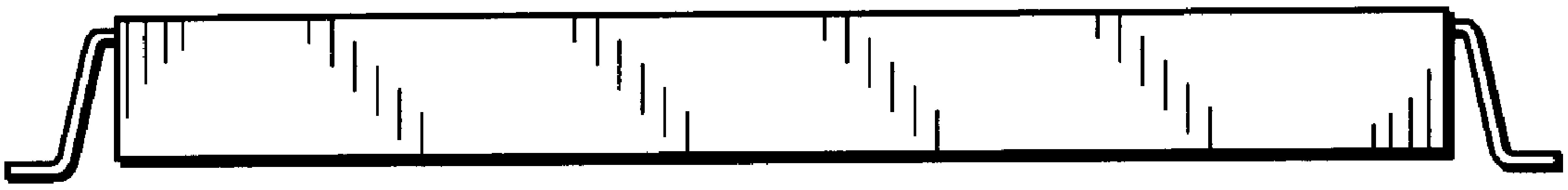


FIG. 3

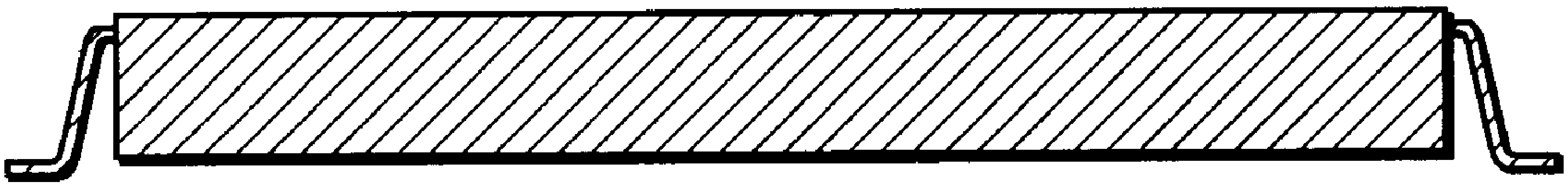


FIG. 4

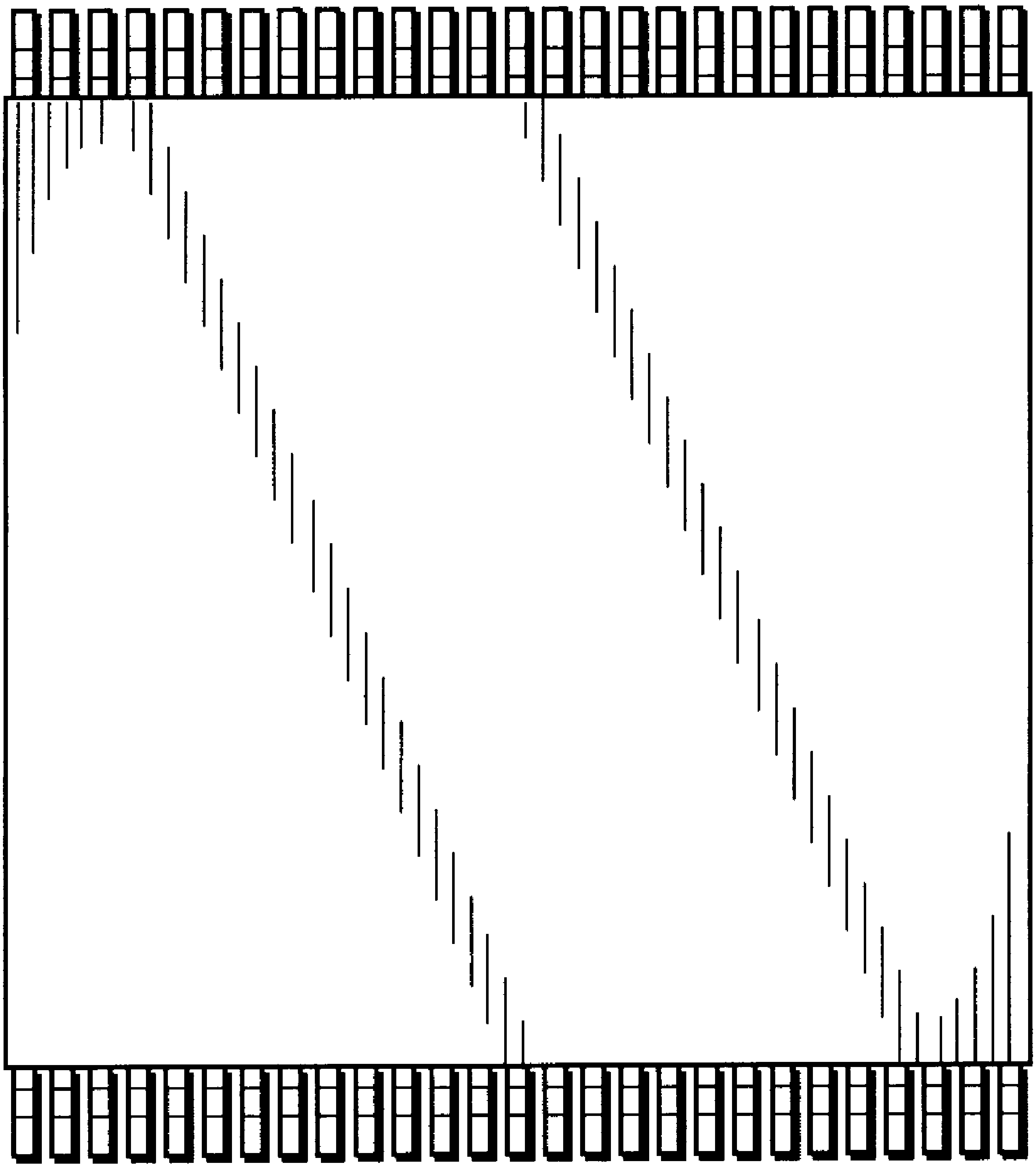


FIG. 5

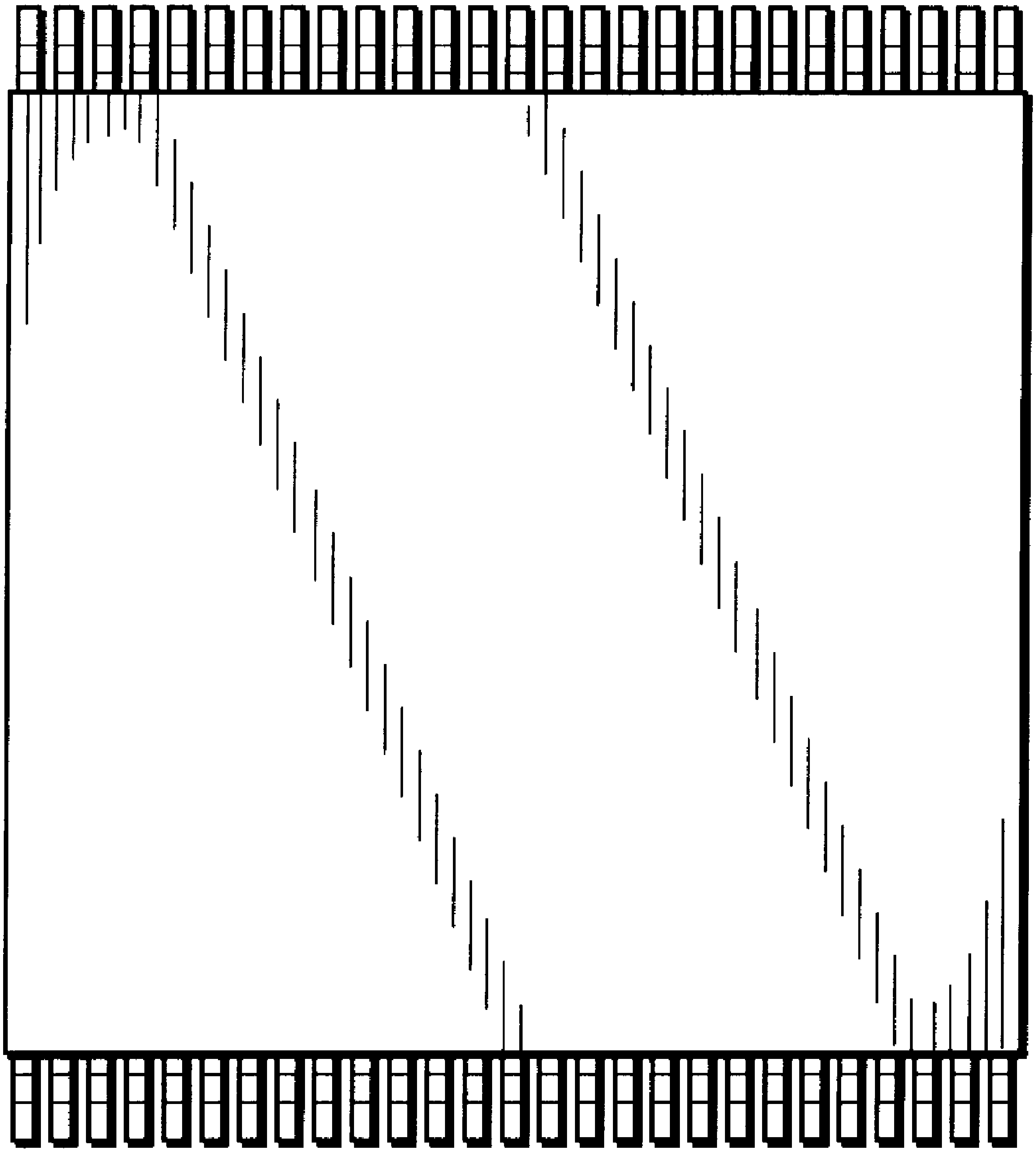


FIG. 6